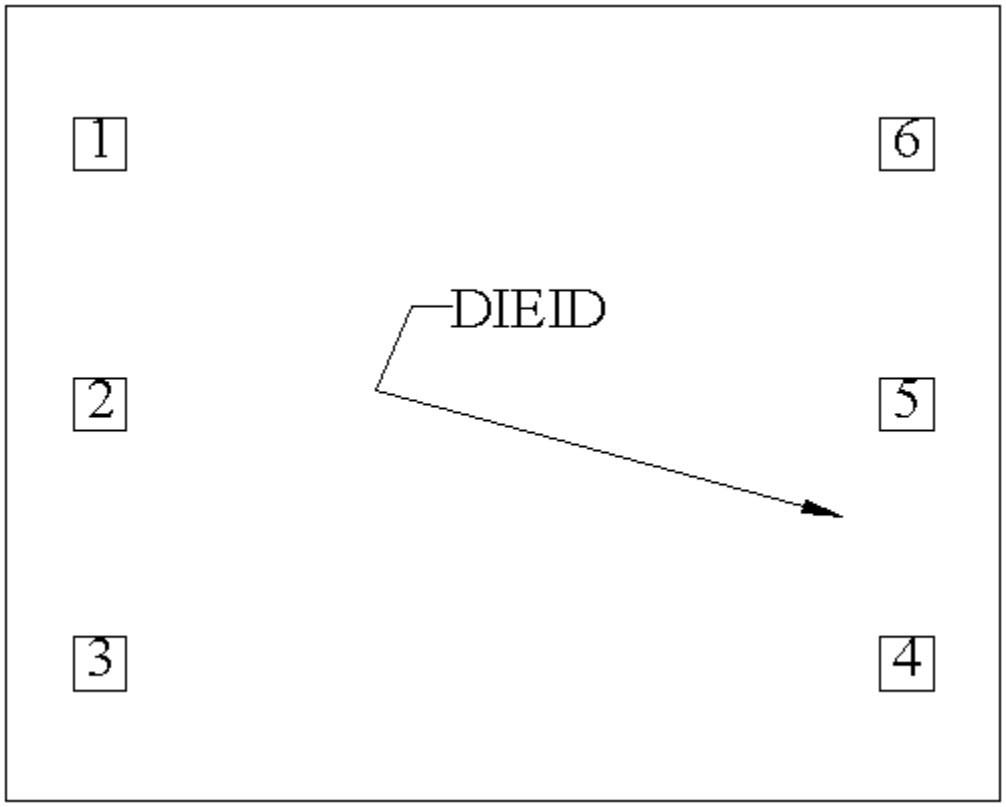
LM71A1- MDA -MWA/S1
+1.0°C ACCURACY, SPI DIGITAL INTERFACE

July 13,2015

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM71A	Bond Pad Opening Size (min)	68μm x 68μm
Die Step	A	Bond Pad Metalization	Al_ 0.5%Cu
Physical Attributes		Passivation	NITRIDE
Wafer Diameter	200mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1270μm x 1016μm 50.0mils x 40.0mils	Back Side Connection	GND
Thickness	254μm Nominal		
Min Pitch	332μm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron. Bond Pad Metal: Composition; Al, 0.5% Cu, Thickness; 8500A

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
CS/	1	-516	332	68	x	68
GND	2	-516	0	68	x	68
V+	3	-516	-332	68	x	68
SC	4	516	-332	68	x	68
GND	5	516	0	68	x	68
SIO	6	516	332	68	x	68

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